

**2K x 8 Static RAM**

**Features**

- Automatic power-down when deselected
- CMOS for optimum speed/power
- High speed
  - 15 ns
- Low active power
  - 660 mW (commercial)
- Low standby power
  - 110 mW (20 ns)
- TTL-compatible inputs and outputs
- Capable of withstanding greater than 2001V electrostatic discharge
- Available in Pb-free and non Pb-free 24-pin Molded SOJ, non Pb-free 24-pin (300-Mil) Molded DIP

**Functional Description**

The CY7C128A is a high-performance CMOS static RAM organized as 2048 words by 8 bits. Easy memory expansion is provided by an active LOW Chip Enable (CE), and active LOW Output Enable (OE) and tri-state drivers. The CY7C128A has an automatic power-down feature, reducing the power consumption by 83% when deselected.

Writing to the device is accomplished when the Chip Enable (CE) and Write Enable (WE) inputs are both LOW.

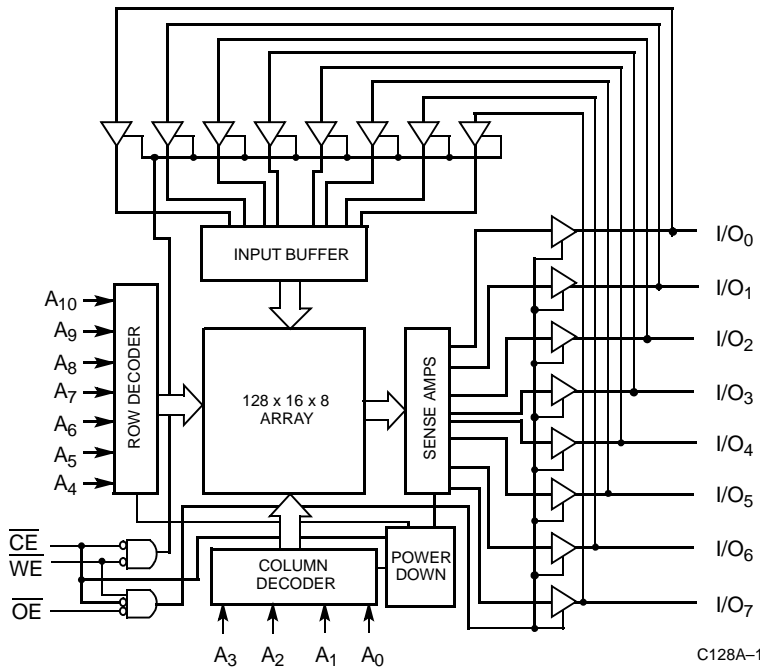
Data on the eight I/O pins (I/O<sub>0</sub> through I/O<sub>7</sub>) is written into the memory location specified on the address pins (A<sub>0</sub> through A<sub>10</sub>).

Reading the device is accomplished by taking Chip Enable (CE) and Output Enable (OE) LOW while Write Enable (WE) remains HIGH. Under these conditions, the contents of the memory location specified on the address pins will appear on the eight I/O pins.

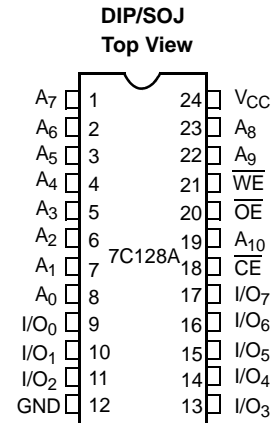
The I/O pins remain in high-impedance state when Chip Enable (CE) or Output Enable (OE) is HIGH or Write Enable (WE) is LOW.

The CY7C128A utilizes a die coat to insure alpha immunity.

**Logic Block Diagram**



**Pin Configurations**



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**Selection Guide**

	-15	-20	-35	-45
Maximum Access Time (ns)	15	20	35	45
Maximum Operating Current (mA)	120	120	120	120
Maximum CMOS Standby Current (mA)	40	20	20	20

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -65°C to +150°C

Ambient Temperature with Power Applied ..... -55°C to +125°C

Supply Voltage to Ground Potential (Pin 28 to Pin 14) ..... -0.5V to +7.0V

DC Voltage Applied to Outputs in High Z State ..... -0.5V to +7.0V

DC Input Voltage ..... -3.0V to +7.0V

Output Current into Outputs (LOW) ..... 20 mA

Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)

Latch-Up Current ..... >200 mA

**Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ± 10%

**Electrical Characteristics Over the Operating Range<sup>[2]</sup>**

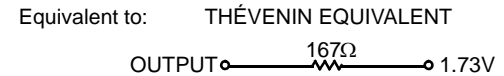
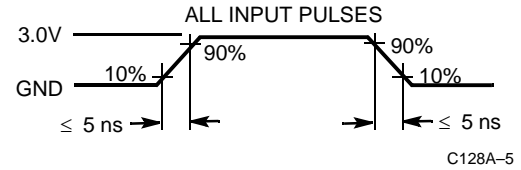
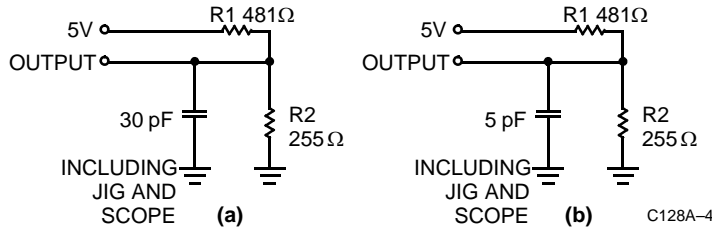
Parameter	Description	Test Conditions	-15		-20		-35, -45		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -4.0 mA	2.4		2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[3]</sup>		-0.5	0.8	-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>	-10	+10	-10	+10	-10	+10	μA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub> Output Disabled	-10	+10	-10	+10	-10	+10	μA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max. I <sub>OUT</sub> = 0 mA		120		120		120	mA
I <sub>SB1</sub>	Automatic $\overline{CE}$ Power-Down Current	Max. V <sub>CC</sub> , $\overline{CE} \geq V_{IH}$ , Min. Duty Cycle = 100%		40		40		20	mA
I <sub>SB2</sub>	Automatic $\overline{CE}$ Power-Down Current	Max. V <sub>CC</sub> , $\overline{CE}_1 \geq V_{CC} - 0.3V$ , V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.3V or V <sub>IN</sub> ≤ 0.3V		40		20		20	mA

**Notes:**

1. T<sub>A</sub> is the "instant on" case temperature.
2. See the last page of this specification for Group A subgroup testing information.
3. V<sub>IL</sub> (min.) = -3.0V for pulse durations less than 30 ns.

**Capacitance<sup>[4]</sup>**

Parameter	Description	Test Conditions	Max.	Unit
$C_{IN}$	Input Capacitance	$T_A = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ , $V_{CC} = 5.0\text{V}$	10	pF
$C_{OUT}$	Output Capacitance		10	pF

**AC Test Loads and Waveforms**

**Switching Characteristics Over the Operating Range<sup>[2, 5]</sup>**

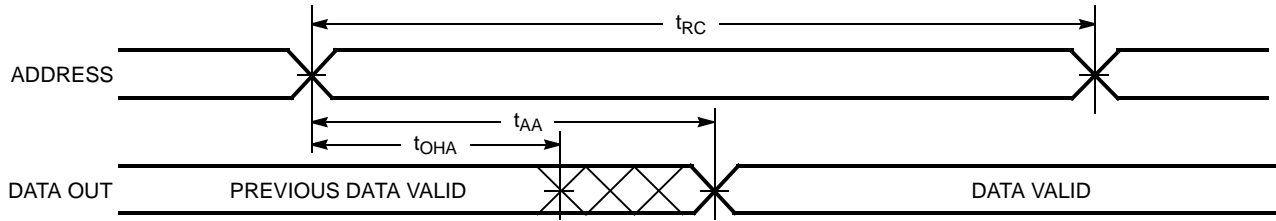
Parameter	Description	-15		-20		-35		-45		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>READ CYCLE</b>										
$t_{RC}$	Read Cycle Time	15		20		35		45		ns
$t_{AA}$	Address to Data Valid		15		20		35		45	ns
$t_{OHA}$	Data Hold from Address Change	5		5		5		5		ns
$t_{ACE}$	$\overline{CE}$ LOW to Data Valid		15		20		35		45	ns
$t_{DOE}$	$\overline{OE}$ LOW to Data Valid		10		10		15		20	ns
$t_{LZOE}$	$\overline{OE}$ LOW to Low Z	3		3		3		3		ns
$t_{HZOE}$	$\overline{OE}$ HIGH to High Z <sup>[6]</sup>		8		8		12		15	ns
$t_{LZCE}$	$\overline{CE}$ LOW to Low Z <sup>[7]</sup>	5		5		5		5		ns
$t_{HZCE}$	$\overline{CE}$ HIGH to High Z <sup>[6, 7]</sup>		8		8		15		15	ns
$t_{PU}$	$\overline{CE}$ LOW to Power-Up	0		0		0		0		ns
$t_{PD}$	$\overline{CE}$ HIGH to Power-Down		15		20		20		25	ns
<b>WRITE CYCLE<sup>[8]</sup></b>										
$t_{WC}$	Write Cycle Time	15		20		25		40		ns
$t_{SCE}$	$\overline{CE}$ LOW to Write End	12		15		25		30		ns
$t_{AW}$	Address Set-Up to Write End	12		15		25		30		ns
$t_{HA}$	Address Hold from Write End	0		0		0		0		ns
$t_{SA}$	Address Set-Up to Write Start	0		0		0		0		ns
$t_{PWE}$	$\overline{WE}$ Pulse Width	12		15		20		20		ns
$t_{SD}$	Data Set-Up to Write End	10		10		15		15		ns
$t_{HD}$	Data Hold from Write End	0		0		0		0		ns
$t_{HZWE}$	$\overline{WE}$ LOW to High Z <sup>[6]</sup>		7		7		10		15	ns
$t_{LZWE}$	$\overline{WE}$ HIGH to Low Z	5		5		5		5		ns

**Notes:**

- Tested initially and after any design or process changes that may affect these parameters
- Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $I_{OL}/I_{OH}$  and 30-pF load capacitance.
- $t_{HZOE}$ ,  $t_{HZCE}$ , and  $t_{HZWE}$  are specified with  $C_L = 5\text{ pF}$  as in part (b) of AC Test Loads. Transition is measured  $\pm 500\text{ mV}$  from steady state voltage.
- At any given temperature and voltage condition,  $t_{HZCE}$  is less than  $t_{LZCE}$  for any given device.
- The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{WE}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

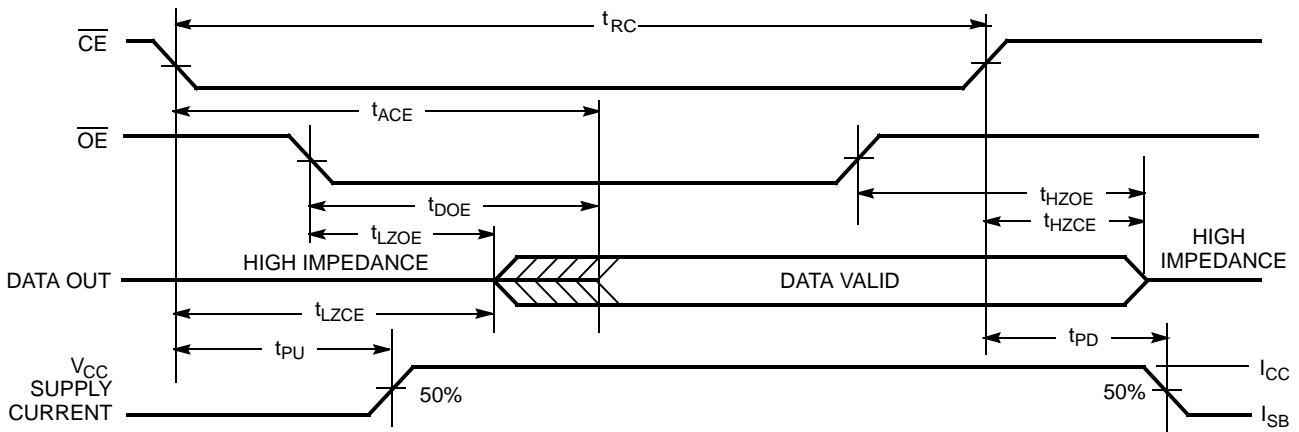
### Switching Waveforms

#### Read Cycle No. 1<sup>[9, 10]</sup>



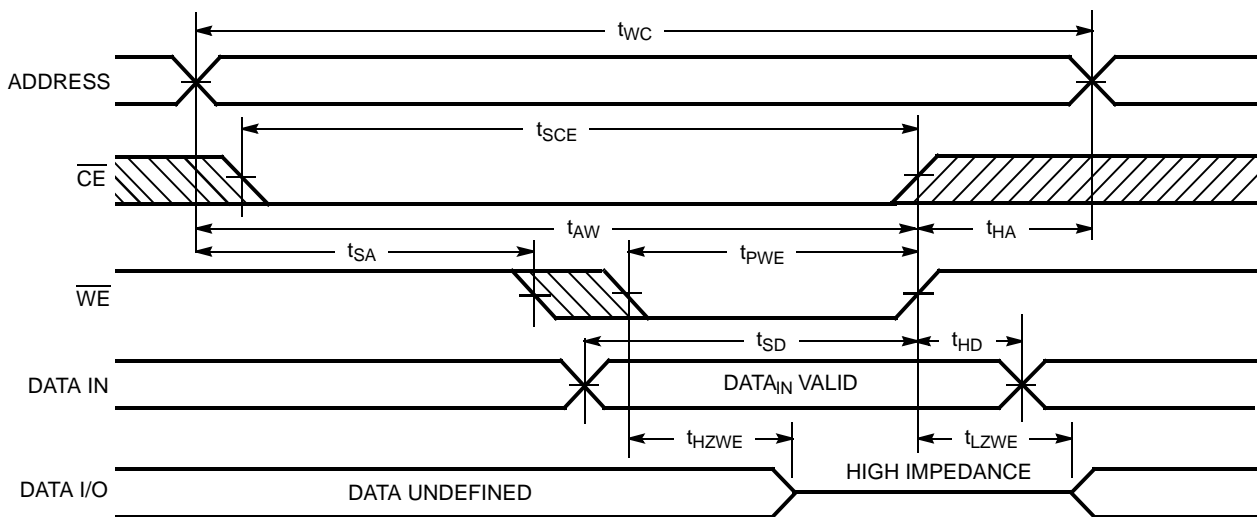
C128A-6

#### Read Cycle No. 2<sup>[9, 11]</sup>



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#### Write Cycle No. 1 ( $\overline{WE}$ Controlled)<sup>[8]</sup>



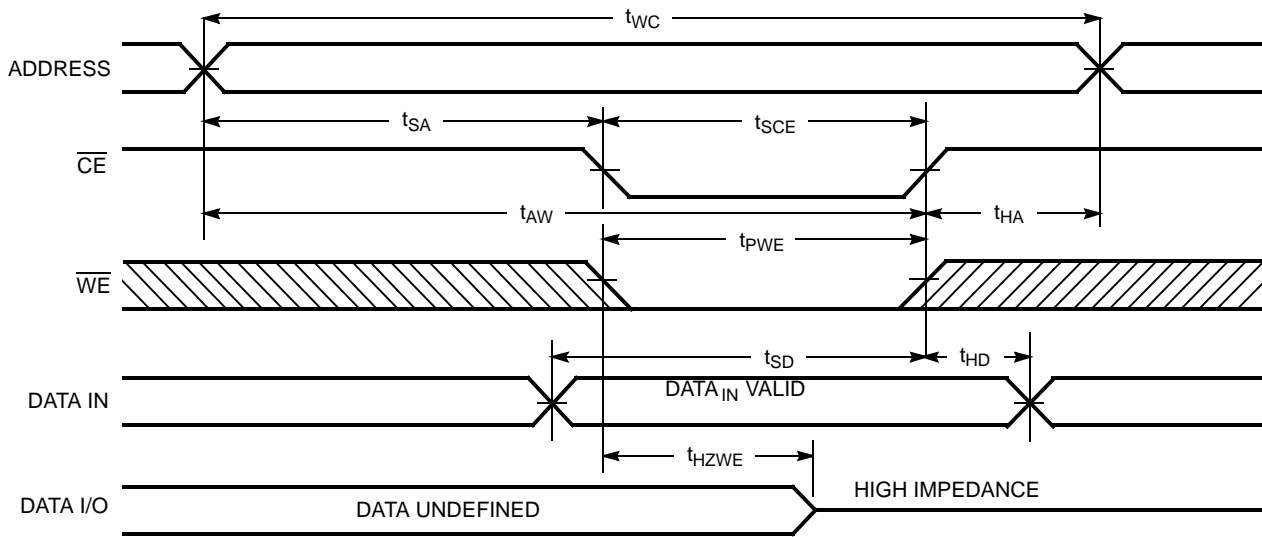
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**Notes:**

- 9. WE is HIGH for read cycle.
- 10. Device is continuously selected.  $\overline{OE}, \overline{CE} = V_{IL}$ .
- 11. Address valid prior to or coincident with CE transition LOW.

Switching Waveforms (continued)

Write Cycle No. 2 ( $\overline{CE}$  Controlled)<sup>[8, 12, 13]</sup>

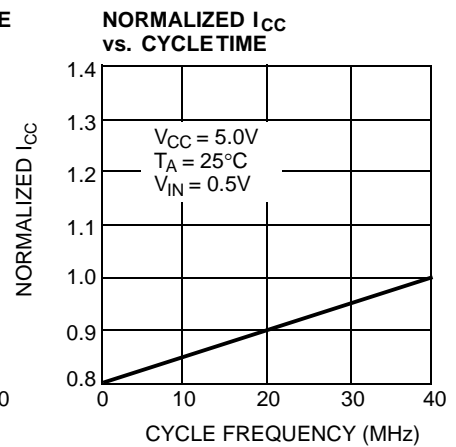
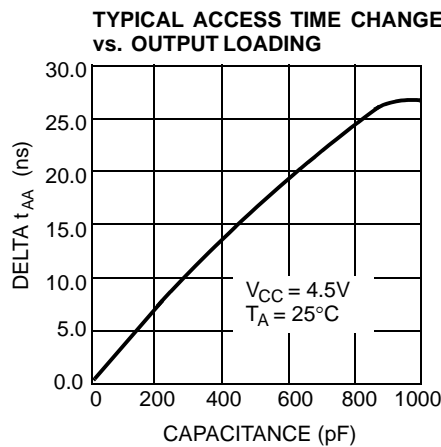
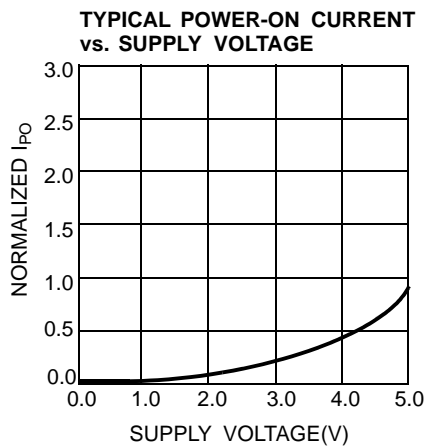
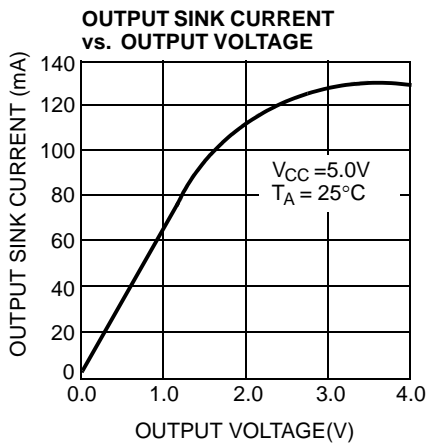
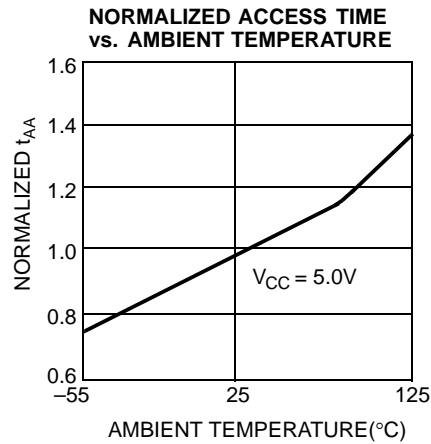
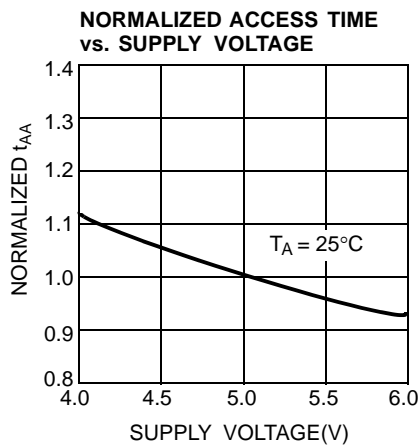
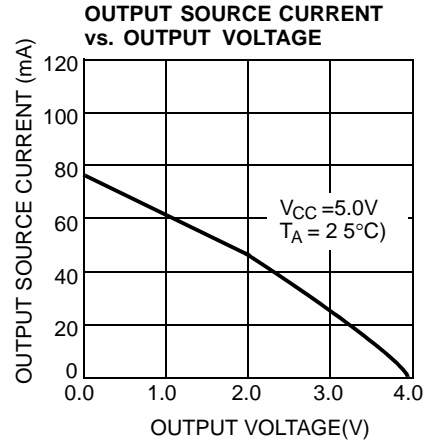
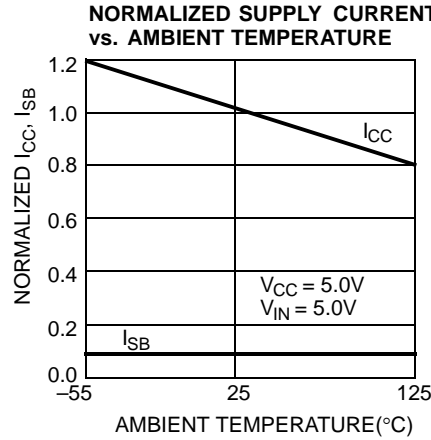
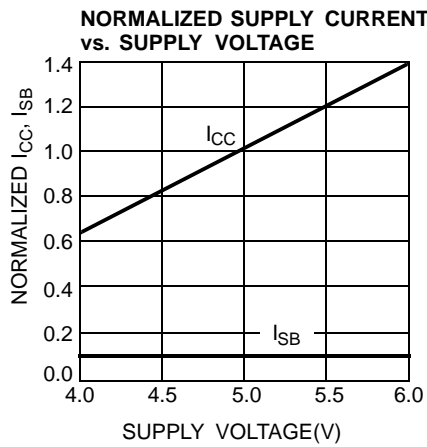


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Notes:

- 12. Data I/O pins enter high-impedance state, as shown, when  $\overline{OE}$  is held LOW during write.
- 13. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high-impedance state.

Typical DC and AC Characteristics



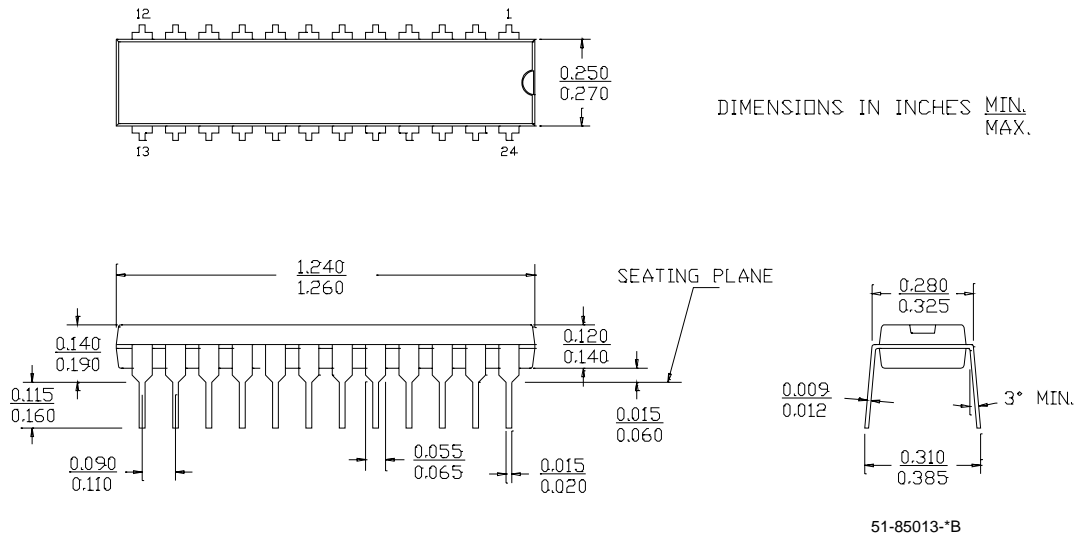
**Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C128A-15PC	51-85013	24-pin (300-Mil) Molded DIP	Commercial
	CY7C128A-15VC	51-85030	24-pin Molded SOJ	
	CY7C128A-15VXC		24-pin Molded SOJ	
20	CY7C128A-20VXC	51-85030	24-pin Molded SOJ (Pb-free)	Commercial
35	CY7C128A-35VC	51-85030	24-pin Molded SOJ	Commercial
45	CY7C128A-45PC	51-85013	24-pin (300-Mil) Molded DIP	Commercial

Please contact local sales representative regarding availability of these parts

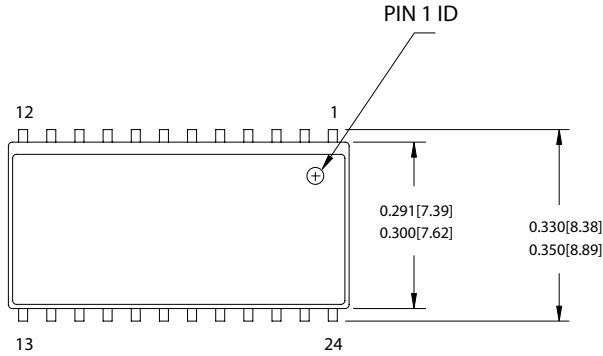
**Package Diagrams**

**24-pin (300-Mil) Molded DIP (51-85013)**



**Package Diagrams (continued)**

**24-pin (300-mil) SOJ (51-85030)**



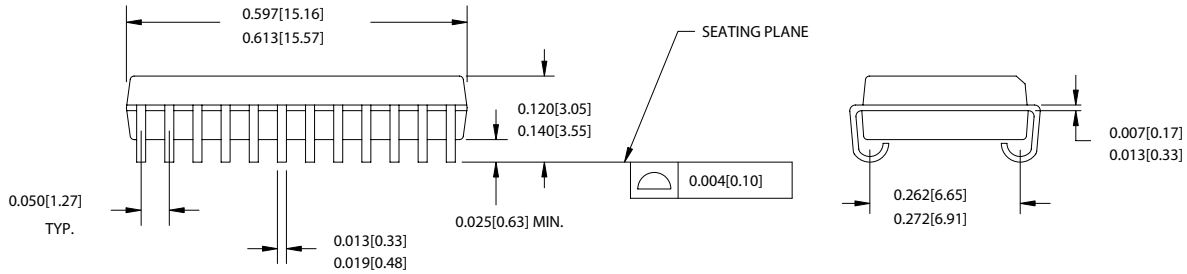
DIMENSIONS IN INCHES[MM]

MIN.  
MAX.

REFERENCE JEDEC MO-088

PACKAGE WEIGHT 0.75gms

PART #	
V24.3	STANDARD PKG.
VZ24.3	LEAD FREE PKG.



51-85030-\*B



**Document History Page**

Document Title: CY7C128A 2K x 8 Static RAM Document Number: 38-05028				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	106814	09/10/01	SZV	Change from Spec number: 38-00094 to 38-05028
*A	493543	See ECN	NXR	Removed 25 ns speed bin Removed Military Operating Range Changed the description of $I_{IX}$ from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed $I_{OS}$ parameter from DC Electrical Characteristics table Updated ordering Information Table